

The logo for TMS 2016 features the letters 'TMS' in a stylized, overlapping font within a blue circular graphic, followed by the year '2016' in a large, bold, black sans-serif font.

TMS 2016

PROFESSIONAL DEVELOPMENT
FEBRUARY 14-18
DOWNTOWN NASHVILLE, TENNESSEE

**BROADEN YOUR EXPERTISE: REGISTER FOR A
PROFESSIONAL DEVELOPMENT EVENT AT TMS2016**

12TH ANNUAL LEAD-FREE SOLDERS AND INTERCONNECT TECHNOLOGY WORKSHOP

SUNDAY, FEBRUARY 14, 2016 • 8:30 A.M. TO 4:30 P.M. (CST)

SPONSORED BY THE TMS FUNCTIONAL MATERIALS DIVISION

**97% OF SURVEYED ATTENDEES AT THE TMS2015 COURSE WERE SATISFIED
OR VERY SATISFIED WITH THE OVERALL PROGRAM OF THIS WORKSHOP.**

ORGANIZERS

Fan Hua, Intel (Lead Organizer); **Fan-Yi Ouyang**, National Tsing Hua University; **Babak Arfaei**, Universal Instrument; **Albert Wu**, National Central University; and **Tae-Kyu Lee**, Cisco

WORKSHOP OVERVIEW

This annual workshop provides the latest development and research studies on interconnect materials and electronic packaging technologies. Due to the miniaturization and multi-functional trends for electronic packages, the key materials used in different levels of packaging have dramatically changed or experienced severe service conditions. The workshop will both introduce the new technology trends and will also provide and address deep-dive discussion topics for both industry and academia.

REGISTRATION FEES*

Register for this professional development event through the TMS 2016 Annual Meeting & Exhibition Registration Form.

Before January 8, 2016	After January 8, 2016
Member \$25	Member \$75
Nonmember \$125	Nonmember \$175
Student \$15	Student \$75

** Registration fees include mid-morning and mid-afternoon refreshment breaks. There will be a mid-day break during which attendees can get lunch on their own.*

Learn more about this workshop at: WWW.TMS.ORG/TMS2016/PBFREE